

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau

(43) International Publication Date
30 September 2021 (30.09.2021)



(10) International Publication Number
WO 2021/190804 A1

(51) International Patent Classification:

C25D 5/02 (2006.01) C25D 17/00 (2006.01)
C25D 5/34 (2006.01) C25D 17/06 (2006.01)
C25D 7/00 (2006.01) C25D 21/12 (2006.01)

(21) International Application Number:

PCT/EP2021/051872

(22) International Filing Date:

27 January 2021 (27.01.2021)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

20165608.9 25 March 2020 (25.03.2020) EP

(71) Applicant: SEMSYSCO GMBH [AT/AT]; Karolinger-
straße 7C, 5020 Salzburg (AT).

(72) Inventors: **LATIFI, Aljbert**; Strubergasse 31/18, 5020
Salzburg (AT). **ÖTZLINGER, Herbert**; Hallwanger Lan-
desstrasse 50, 5300 Hallwang (AT). **MARKUT, Franz**;
Hofwiesenstrasse 36, 9423 St. Georgen (AT). **GLEISSN-
ER, Andreas**; Steinwandweg 3, 9873 Döbriach (AT).

(74) Agent: **MAIWALD PATENTANWALTS- UND
RECHTSANWALTSGESELLSCHAFT MBH**; Post-
fach 33 05 23, 80065 München (DE).

(81) Designated States (*unless otherwise indicated, for every
kind of national protection available*): AE, AG, AL, AM,
AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ,
CA, CH, CL, CN, CO, CR, CU, CZ, DE, DJ, DK, DM, DO,
DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN,
HR, HU, ID, IL, IN, IR, IS, IT, JO, JP, KE, KG, KH, KN,
KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD,
ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO,
NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW,

(54) Title: METHOD FOR A CHEMICAL AND/OR ELECTROLYTIC SURFACE TREATMENT OF A SUBSTRATE IN A PRO-
CESS STATION

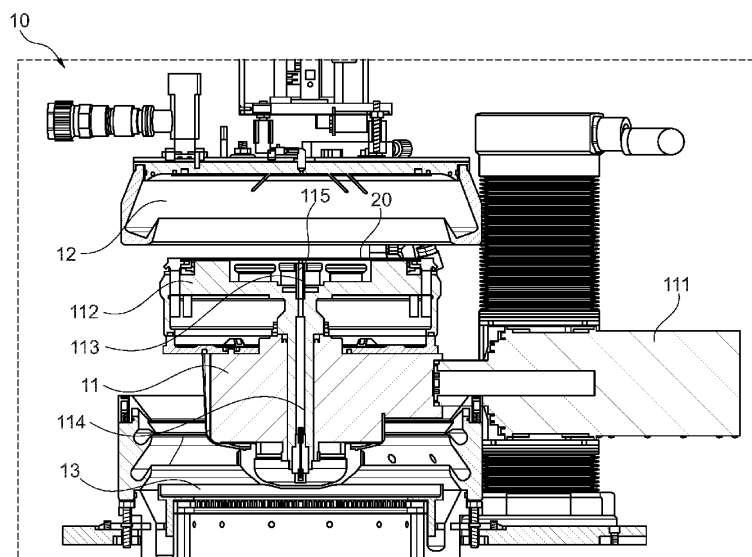


Fig. 1

(57) Abstract: The invention relates to a method for a chemical and/or electrolytic surface treatment of a substrate in a process station and a process station for a chemical and/or electrolytic surface treatment of a substrate. The method for a chemical and/or electrolytic surface treatment comprises the following steps, not necessarily in this order: mounting a substrate to be treated to a rotor unit, moving the rotor unit with the substrate into a pre-wetting chamber of the process station, applying a pre-wetting fluid to the substrate in the pre-wetting chamber, moving the rotor unit with the substrate at least partially out of the pre -wetting chamber, spinning the rotor unit with the substrate in a spinning plane to centrifugally reduce the pre-wetting fluid at a surface of the substrate, rotating the rotor unit with the substrate normal to the spinning plane so that the substrate faces away from the pre -wetting chamber, moving the rotor unit with the substrate into an electroplating chamber of the process station, applying an electrolyte liquid and an electric current to the

[Continued on next page]

WO 2021/190804 A1

SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH, TJ, TM, TN,
TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS, ZA, ZM, ZW.

(84) Designated States (*unless otherwise indicated, for every kind of regional protection available*): ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, ST, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Published:

— with international search report (Art. 21(3))

substrate for an electroplating process on the substrate in the electroplating chamber, and moving the rotor unit with the substrate at least partially out of the electroplating chamber.